

IGBT - Power, Single N-Channel, Field Stop VII (FS7), SCR, Power TO247-3L

1200 V, 1.42 V, 40 A

AFGHL40T120RW

Description

Using the novel field stop 7th generation IGBT technology in TO247 3-lead package, this device offers the optimum performance with low on state voltage and minimal switching losses for both hard and soft switching topologies in automotive applications.

Features

- Extremely Efficient Trench with Field Stop Technology
- Maximum Junction Temperature T_J =175°C
- Short Circuit Rated / Low Saturation Voltage
- Fast Switching / Tightened Parameter Distribution
- AEC-Q101 Qualified, PPAP Available Upon Request
- This Device is Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Automotive E-compressor
- Automotive EV PTC Heater
- OBC

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

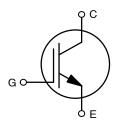
Pai	Symbol	Value	Unit	
Collector-to-Emitter V	V_{CE}	1200	V	
Gate-to-Emitter Volta	V_{GE}	±20		
Transient Gate-to-Em		±30		
Collector Current $T_C = 25^{\circ}C$		I _C	80	Α
	T _C = 100°C		40	
Power Dissipation	T _C = 25°C	P_{D}	576	W
	T _C = 100°C		288	
Pulsed Collector $T_C = 25^{\circ}C$, Current $t_p = 10 \mu s$ (Note 1)		I _{CM}	120	Α
Short Circuit Withstand V _{GE} = 15 V, V _{CC} = 800	T _{SC}	6	μs	
Operating Junction an Range	T _J , T _{stg}	-55 to +175	°C	
Lead Temperature for	TL	260	1	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

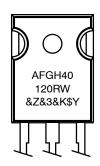
BV _{CES}	V _{CE(sat)} TYP	I _C MAX
1200 V	1.42 V	40 A

PIN CONNECTIONS





MARKING DIAGRAM



AFGH40120RW = Specific Device Code
&Z = Assembly Plant Code
&3 = 3-Digit Date Code
&K = 2-Digit Lot Traceability Code
\$Y = onsemi Logo

ORDERING INFORMATION

Device	Package	Shipping
AFGHL40T120RW	TO-247-3L (Pb-Free)	30 Units / Tube

^{1.} Repetitive rating: Pulse width limited by max. junction temperature

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case for IGBT	$R_{ heta JC}$	0.26	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{ hetaJA}$	40	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS				-		•
Collector-to-Emitter Breakdown Voltage	BV _{CES}	V _{GE} = 0 V, I _C = 5 mA	1200	-	-	V
Zero Gate Voltage Collector Current	I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	-	-	40	μΑ
Gate-to-Emitter Leakage Current	I _{GES}	V _{GE} = ±20 V, V _{CE} = 0 V	-	-	±400	nA
ON CHARACTERISTICS						
Gate-to-Emitter Threshold Voltage	V _{GE(th)}	$V_{GE} = V_{CE}$, $I_C = 40 \text{ mA}$	5.03	5.93	6.83	V
Collector-to-Emitter Saturation	V _{CE(sat)}	V _{GE} = 15 V, I _C = 40 A, T _J = 25°C	-	1.42	1.75	V
Voltage		V _{GE} = 15 V, I _C = 40 A, T _J = 175°C	-	1.68	-	1
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{IES}	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	-	4717	-	pF
Output Capacitance	C _{OES}		-	144	-	
Reverse Transfer Capacitance	C _{RES}		-	24.5	-	
Total Gate Charge	Q_{G}	V _{CE} = 600 V, V _{GE} = 15 V, I _C = 40 A	-	171	-	nC
Gate-to-Emitter Charge	Q_{GE}		-	42.2	-	
Gate-to-Collector Charge	Q_{GC}		-	73.7	-	
SWITCHING CHARACTERISTICS, IN	DUCTIVE LOA	AD (Note: Si Diode Applied)				
Turn-On Delay Time	t _{d(on)}	V _{CE} = 600 V	_	50.1	-	ns
Turn-Off Delay Time	t _{d(off)}	$V_{GE} = 0/15 \text{ V}$ $I_{C} = 20 \text{ A}$	_	293	-]
Rise Time	t _r	$R_G = 4.7 \Omega$ $T_{,l} = 25^{\circ}C$	_	30.9	-	
Fall Time	t _f		_	189	-	
Turn-On Switching Loss	E _{on}]	_	1.37	-	mJ
Turn-Off Switching Loss	E _{off}		_	1.35	-	
Total Switching Loss	E _{ts}		-	2.72	-	
Turn-On Delay Time	t _{d(on)}	V _{CE} = 600 V	_	55.2	-	ns
Turn-Off Delay Time	t _{d(off)}	$V_{GE} = 0/15 \text{ V}$ $I_{C} = 40 \text{ A}$	-	241	-	
Rise Time	t _r	$R_G = 4.7 \Omega$ $T_J = 25^{\circ}C$	-	55.2	-	
Fall Time	t _f		-	122	-	
Turn-On Switching Loss	E _{on}		-	3.68	-	mJ
Turn-Off Switching Loss	E _{off}		-	1.7	-	
Total Switching Loss	E _{ts}]	-	5.38	-	1

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified) (continued)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS, INDUCTIVE LOAD (Note: Si Diode Applied)						
Turn-On Delay Time	t _{d(on)}	V _{CE} = 600 V	-	56	-	ns
Turn-Off Delay Time	t _{d(off)}	$V_{GE} = 0/15 \text{ V}$ $I_{C} = 20 \text{ A}$	=	414	-	1
Rise Time	t _r	R _G = 4.7 Ω T _J = 175°C	=	41.7	-	1
Fall Time	t _f		-	375	-	
Turn-On Switching Loss	E _{on}		-	2.13	-	mJ
Turn-Off Switching Loss	E _{off}		-	2.51	-	
Total Switching Loss	E _{ts}		_	4.64	-	
Turn-On Delay Time	t _{d(on)}	V _{CE} = 600 V	-	63.1	-	ns
Turn-Off Delay Time	t _{d(off)}	$V_{GE} = 0/15 \text{ V}$ $I_{C} = 40 \text{ A}$ $R_{G} = 4.7 \Omega$ $T_{J} = 175^{\circ}\text{C}$	-	325	-	
Rise Time	t _r		_	71.2	-	
Fall Time	t _f		-	233	-	1
Turn-On Switching Loss	E _{on}		-	5.75	-	mJ
Turn-Off Switching Loss	E _{off}		-	3.03	-	
Total Switching Loss	E _{ts}		_	8.79	-	1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

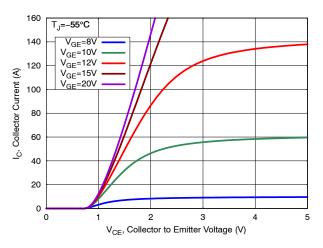


Figure 1. Output Characteristics

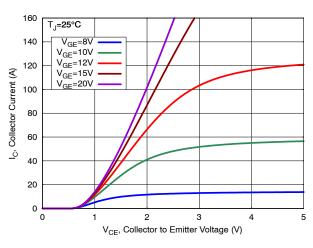


Figure 2. Output Characteristics

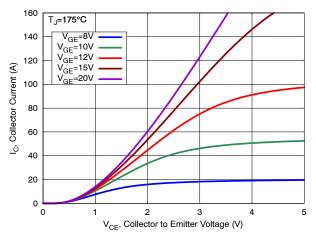


Figure 3. Output Characteristics

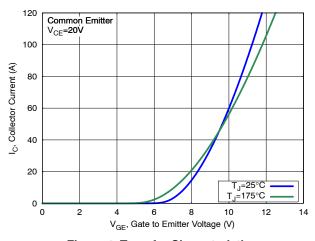


Figure 4. Transfer Characteristics

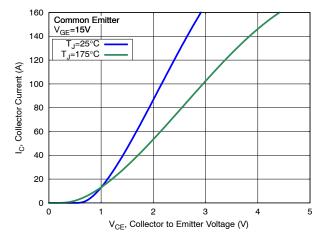


Figure 5. Saturation Characteristics

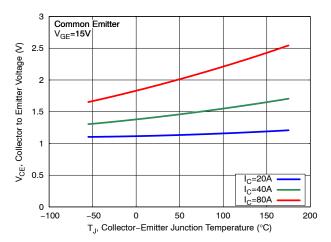


Figure 6. Saturation Voltage vs Junction Temperature

TYPICAL CHARACTERISTICS

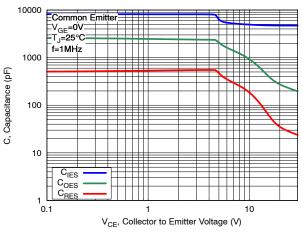


Figure 7. Capacitance Characteristics

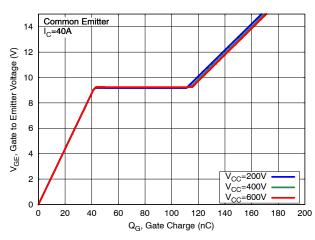


Figure 8. Gate Charge Characteristics

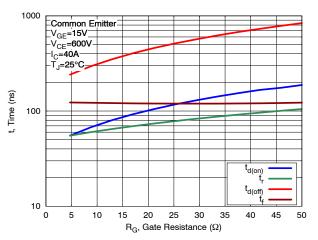


Figure 9. Switching Time vs Gate Resistance

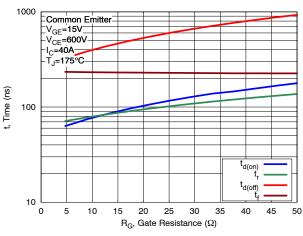


Figure 10. Switching Time vs Gate Resistance

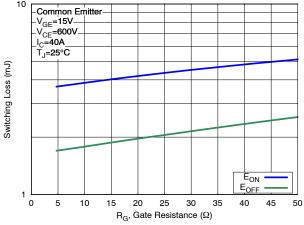


Figure 11. Switching Loss vs Gate Resistance

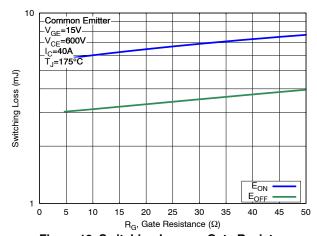


Figure 12. Switching Loss vs Gate Resistance

TYPICAL CHARACTERISTICS

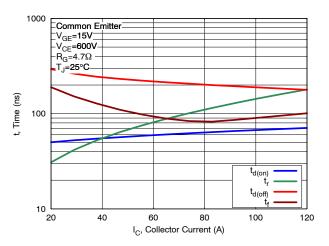
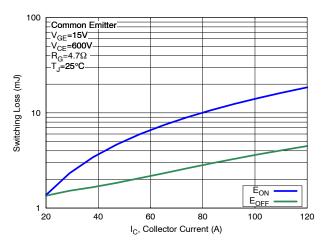


Figure 13. Switching Time vs Collector Current

Figure 14. Switching Time vs Collector Current



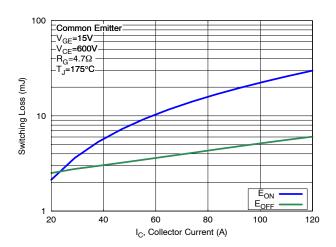


Figure 15. Switching Loss vs Gate Resistance

Figure 16. Switching Loss vs Collector Current

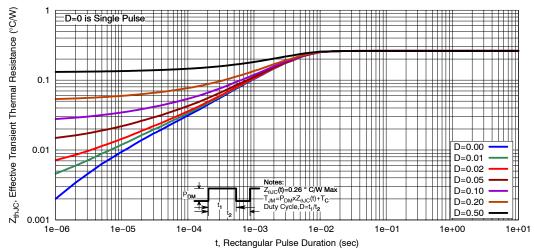
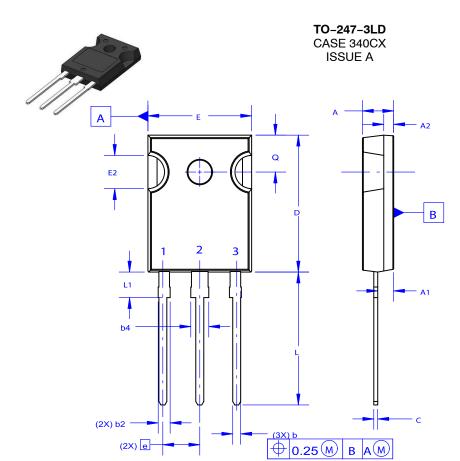
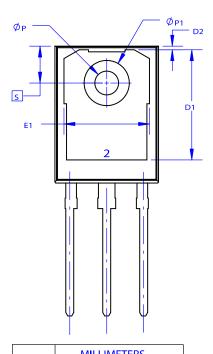


Figure 17. Transient Thermal Impedance of IGBT



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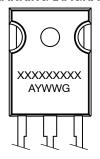


NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

 B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code = Assembly Location

= Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " =", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A 1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
Ø P 1	6.60	6.80	7.00		

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